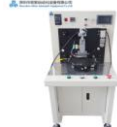













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website:

TV Laptop COF Bonding Machines						
NO.	Category	Picture	Specification		Function	Price
	COF Bonding Machine		Model:	OL-1285SH-SS	*Pulse Heating System *4PCS CCD *Panasonic PLC Control system *Human - Machine interface *Imported electrical configuration *Up to 85inch TV LCD Repair *Glass Platform movable	
			Product Name:	COF single station Pulse Heating Bonding machine		
			Suitable For:	Suitable for COF Contraposition bonded to LCD Glass and PCB which attached ACF.Used for COF repair		
			Size Range:	12.85inch		
			Bonding Precision:	X±0.01MM, Y±0.01MM		
			Machine Capacity:	12S/Pcs		
			Indenter Qty:	1PCS		
			Power Supply:	220V±10%, 50HZ, 2000W		
			Air Supply:	0.4-0.7MPa, dry air		
			FPC size:	Max:L80*W60MM Min:L10*W15MM		
			Platform Precision:	±0.01MM		
			Pressure Head Size:	80*1MM (customizable)		
			Temp Range:	RT-400℃		
			Time Range:	1-99.9sec		
			Product Size:	W1200*1200*H1380MM		
			N.W:	About 500kg		
			Packing Size:			
			G.W:	About 600kg 6CBM		
	COF Bonding Machine		Model:	OL-1285DH-SS	*Pulse Heating System *4PCS CCD *Panasonic PLC Control system *Human - Machine interface *Imported electrical configuration *Up to 85inch TV LCD Repair *Glass Platform movable	
			Product Name:	COF Double stations Pulse Heating Bonding machine		
			Suitable For:	Suitable for FPC/COF Contraposition bonded to LCD glass and PCB which attached ACF.Used for COF repair		
			Size Range:	12.85inch		
			Bonding Precision:	X±0.01MM, Y±0.01MM		
			Bonding Capacity:	12S/Pcs.		
			Indenter Qty:	1PCS		
			Power Supply:	220V±10%, 50HZ, 4000W		
			Air Supply:	0.4-0.7MPa, dry air		
			FPC size:	Max:L80*W60MM Min:L10*W15MM		
			Platform Precision:	±0.01MM		
			Pressure Head Size:	80*1MM (customizable)		
			Temp Range:	RT-400℃		
			Time Range:	1-99.9sec		
			Product Size:	W1200*1200*H1380MM		
			N.W:	About550kg		
			Packing Size:			
			G.W:	About 650kg 6CBM		
LCM Small Size Equipment						
ACF Attach Machine						
NO.	Category	Picture	Specification		Function	EXW Price(USD)
	ACF Attach M/C		Model:	AA003	*Constant temperature heating system *Panasonic PLC Control system *Human-machine interface *ACF Attach length calculated automatically *Pressure head horizontal adjustment device *Manual / automatic switching *Accurate ACF transport system *Automatic cutting device *Imported electrical configuration	
			Product Name:	1-12" Semi-automatic single-side, single-segment ACF attach M/C		
			Suitable for:	ACF attached to LCD/FPC/PCB soft&hard base material		
			Size Range:	1-12 inch		
			Attach Precision:	X ±0.15MM, Y±0.1MM		
			ACF Width:	0.8-6MM		
			Machine Capacity:	4Sec/pcs, 900pcs/H		
			Power Supply:	220V±10%, 50HZ, 500W		
			Air Supply:	0.4-0.6MPa, Dry air		
			Air Consumption:	120L/min		
			Pressure Head Size:	90*5MM(Customizable)		
			Temp Range:	1-300℃		
			Time Range:	0.1-99.9 Seconds		
			Product Size:	W650*D700*H1450MM		
			N.W:	About 100KG		
			Packing Size:			
			G.W:			
	ACF Attach M/C		Model:	AA006	*Constant temperature heating system *Panasonic PLC Control system *Human-machine interface *ACF Attach length calculated automatically *Pressure head horizontal adjustment device *Manual / automatic switching *Accurate ACF transport system *Automatic cutting device *Imported electrical configuration	
			Product Name:	1-12" Semi-automatic single-side, Multi-segment ACF attach M/C		
			Suitable for:	ACF attached to LCD/FPC/PCB soft&hard base material		
			Size Range:	1-12 inch		
			Attach Precision:	X ±0.15MM, Y±0.1MM		
			ACF Width:	0.8-6MM		
			Machine Capacity:	4S/pcs, 900pcs/H		
			Power Supply:	220V±10%, 50HZ, 1000W		
			Air Supply:	0.4-0.7MPa, Dry air		
			Air Consumption:	120L/min		
			Pressure Head Size:	90*5MM(Customizable)		
			Temp Range:	1-300℃		
			Time Range:	0.1-99.9 Seconds		
			Product Size:	W1200*D1000*H1600MM		
			N.W:	About 200KG		
			Packing Size:			
			G.W:			
COG Pre-Bonding Machine						
NO.	Category	Picture	Specification		Function	Price
	COG Pre-bonding M/C		Model:	CP005	*Suitable for multi variety small batch production *Constant temperature heating system *Panasonic PLC Control system *FAST Visual processing system *Imported Japanese CCD Automatic Contraposition Configuration *Manual / automatic switching *Imported electrical configuration	
			Product Name:	Semi-Automatic Mid-speed COG Pre-Press M/C		
			Suitable For:	Suitable for IC bonded to the LCD which attached ACF		
			Size Range:	1-7 inch		
			Attach Precision:	±2.5UM		
			IC Size:	L:2-40mm, W:0.8-3mm		
			Machine Capacity:	650pcs/H		
			Power Supply:	220V±10%, 50HZ, 1000W		
			Air Supply:	0.5-0.7MPa, dry air		
			Platform Size:	140*100MM		
			Platform Precision:	±0.01MM		
			Pressure Head Size:	40*2MMcustomizable		
			Temp Range:	1-300℃		
			Time Range:	1-99.9		
			Product Size:	850*600*1370MM		
			N.W:	About 150KG		
			Packing Size:			
			G.W:			
	COG Pre-bonding M/C		Model:	CP006	*Suitable for mass production *Constant temperature heating system *Panasonic PLC Control system *Panasonic Visual processing system *Imported electrical configuration *Imported Japanese CCD Automatic Contraposition Configuration	
			Product Name:	Semi-Automatic High-speed COG Pre-Press M/C		
			Suitable For:	Suitable for IC bonded to the LCD which attached ACF		
			Size Range:	1-7 inch		
			Attach Precision:	±2.5UM		
			IC Size:	L:2-40mm, W:0.8-3mm		
			Machine Capacity:	1000pcs/H		
			Power Supply:	220V±10%, 50HZ, 1000W		
			Air Supply:	0.5-0.7MPa, dry air		
			Platform Size:	140*100MM		
			Platform Precision:	±0.01MM		
			Pressure Head Size:	40*2MMcustomizable		
			Temp Range:	1-300℃		
			Time Range:	1-99.9sec		
			Product Size:	1100*960*1650MM		
			N.W:	About150KG		
			Packing Size:			
			G.W:			

COG Main-Bonding Machine						
NO.	Category	Picture	Specification	Function	Price	
	COG main-bonding Machine		Model: CM006 Product Name: 1-12 inch Triple Stations Semi-Automatic High-speed COG Press Suitable For: Suitable for IC Bonded to the Panel Size Range: 1-12 inch Attach Precision: $\pm 4.5\mu\text{M}$ IC Size: L:2-40mm, W:0.8-3mm Machine Capacity: 1100pcs/H Power Supply: 220V $\pm 10\%$, 50HZ 2000W Air Supply: 0.5-0.7MPa dry air Platform Size: 150*100MM Platform Precision: $\pm 0.01\text{MM}$ Pressure Head Size: L45*W5MM,customizable Temp Range: RT-400℃ Time Range: 0.1-99.9sec Product Size: L1025*W750*H1400MM Operate Height: 830 $\pm 10\text{mm}$ N.W: About350KG Packing Size: G.W:	*Constant Temp Heating System *Panasonic PLC Control system *Use high precision low-friction cylinder control pressure to ensure the accuracy of pressure control *Use servo motor control movement, cylinder control pressure, to keep the balance between high capacity and stability *Imported electrical configuration		
	COG main-bonding Machine		Model: CM008 Product Name: 1-12 inch Double Stations Semi-Automatic servo COG bonding Machine Suitable For: Suitable for IC Bonded to the Panel. FOR OLED panel Size Range: 1-12 inch Attach Precision: $\pm 4.5\mu\text{M}$ IC Size: L:2-40mm, W:0.8-3mm Machine Capacity: 600pcs/H Power Supply: 220V $\pm 10\%$, 50HZ 1200W Air Supply: 0.5-0.7MPa dry air Platform Size: 150*100MM Platform Precision: $\pm 0.01\text{MM}$ Pressure Head Size: L45*W5MM,customizable Temp Range: RT-400℃ Time Range: 0.1-99.9sec Product Size: L640*W700*H1320MM Operate Height: 800 $\pm 10\text{mm}$ N.W: About 320KG Packing Size: G.W:	*PID Control Constraint Temp Heating System, Automatic temperature compensation to ensure that the temperature of hot pressing is stable *Panasonic PLC Control system *Use high precision low-friction cylinder control pressure to ensure the accuracy of pressure control *High steel structure set, dual ceramic indenter configuration, to ensure the stability of the equipment *Imported electrical configuration. * for OLED high-end products, high quality, high successful rate.		

FOG Bonding Machine						
NO.	Category	Picture	Specification	Function	Price	
	FOG Bonding M/C		Model: FC002 Product Name: Single head Up&Down Contraposition FOG Bonding M/C Suitable For: Suitable for alignment and press the FPC to the LCD Panel which already attached ACF Size Range: 1~7 inch Attach Precision: ±0.015mm Machine Capacity: 3000pcs/days (12S/pc) Power Supply: 220V±10%, 50HZ, 1200W Air Supply: 0.5~0.7MPa dry air FPC Size: Max:L90*W60 Min:L5*W15 Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W650*D880*H1460MM N.W: About200KG Packing Size: G.W:	*Constant temperature heating system *PLC Control System *Human - Machine interface *Automatic temperature alarm *Press Head Level Adjustable Device *Up&Down Contraposition HD Colorful CCD and 10.4 inch HD LCD *Manual / automatic switching *Imported electrical configuration		
	FOG Bonding M/C		Model: FC003 Product Name: Down Contraposition FOG Bonding M/C Suitable For: Suitable for alignment and press the FPC to the LCD Panel which already attached ACF Size Range: 1~12 inch Attach Precision: ±0.015mm Machine Capacity: 6000pcs/days (12S/pc) Power Supply: 220V±10%, 50HZ, 2000W Air Supply: 0.5~0.7MPa dry air FPC Size: Max:L90*W60 Min:L5*W15 Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W850*D710*H1380MM N.W: About220KG Packing Size: G.W:	*Constant temperature heating system *PLC Control System *Human - Machine interface *Automatic temperature alarm *Press Head Level Adjustable Device *Down Contraposition HD Colorful CCD and 10.4 inch HD LCD *Manual / automatic switching *Imported electrical configuration		
	FOG Bonding M/C		Model: FC005/006 Product Name: Up or Down Contraposition Movable platform by track FOG Bonding Suitable For: Suitable for alignment and press FPC to the LCD Panel which attached Size Range: 1~7 inch Attach Precision: ±0.015mm Machine Capacity: 6000pcs/H (12S/pc) Power Supply: 220V±10%, 50HZ, 1200W Air Supply: 0.5~0.7MPa dry air Platform Size: Max:L90*W60 Min:L5*W15 Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W750*D880*H1460MM N.W: About200KG Packing Size: G.W:	*Constant temperature heating system *PLC Control System *Human - Machine interface *Automatic temperature alarm *Press Head Level Adjustable Device *Down Contraposition HD Colorful CCD and 10.4 inch HD LCD *Manual / automatic switching *Imported electrical configuration		
	FOG Bonding M/C		Model: FC007 Product Name: Upper and Down Contraposition movable platform FOG Bonding M/C Suitable For: Suitable for alignment and press FPC to the LCD Panel which attached Size Range: 1~12 inch Attach Precision: ±0.015mm Machine Capacity: 6000pcs/day (12S/pc) Power Supply: 220V±10%, 50HZ, 1200W Air Supply: 0.5~0.7MPa dry air Platform Size: L90*W60 MM Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W850*D880*H1460MM N.W: About200KG Packing Size: G.W:	*Constant temperature heating system *Panasonic PLC Control system *Human - Machine interface *Automatic temperature alarm *Press Head Level Adjustable Device *Down Contraposition HD Colorful CCD and 10.4 inch HD LCD *Manual / automatic switching *Imported electrical configuration *good for ONCELL, OLED panels		
	FOG Pulse Bonding M/C		Model: FP011 Product Name: Upper and Down Contraposition Pulse Bonding machines Suitable For: Suitable for High density FPC/FFC to PCB Hot pressing welding production process Size Range: 1~9 inch Attach Precision: ±0.015mm Machine Capacity: 2800pcs/day (12S/pc) Power Supply: 220V±10%, 50HZ, 3000W Air Supply: 0.5~0.7MPa dry air Platform Size: L90*W60 MM Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W600*D650*H1320MM N.W: About150KG Packing Size: G.W:	*Panasonic PLC Control system *Titanium alloy press head, not easily deformed by high Temp *Pulse heating system, real-time display temperature curve *Signle indenters, HD Colorful CCD Upper and Down Contraposition *Imported electrical configuration		
	FOG Pulse Bonding M/C		Model: FP008 (Upper) /009 (Down) Product Name: Upper (Down) Contraposition Pulse Bonding M/C Suitable For: Suitable for High density FPC/FFC to PCB Hot pressing welding production process Size Range: 1~12 inch Attach Precision: ±0.015mm Machine Capacity: 6000pcs/day (12S/pc) Power Supply: 220V±10%, 50HZ, 2500W Air Supply: 0.5~0.7MPa dry air Platform Size: L60*W60 MM Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W900*D800*H1400MM N.W: About320KG Packing Size: G.W:	*Panasonic PLC Control system *Titanium alloy press head, not easily deformed by high Temp *Pulse heating system, real-time display temperature curve *Double indenters, HD Colorful CCDUpper Contraposition *Imported electrical configuration		
	FOG Pulse Bonding M/C		Model: FP010 Product Name: 1~7 inch Up Contraposition Three Stations Pulse Heating Bonding Suitable For: Suitable for High density FPC bonded to Sensor Glass Size Range: 1~7 inch Attach Precision: ±0.015mm Machine Capacity: 5400pcs/H Power Supply: 220V±10%, 50HZ, 2000W Air Supply: 0.5~0.7MPa dry air Platform Size: L60*W60 MM Platform Precision: ±0.01MM Temp Range: 1~350℃ Time Range: 1~99.9sec Product Size: W700*D800*H1350MM N.W: About320KG Packing Size: G.W:	*Panasonic PLC Control system *Titanium alloy press head, not easily deformed by high Temp *High Precision Pulse heating system, real-time display temperature curve *Discharge, welding, taking three stations, Rotatable platform, only discharge manually, welding and taking automatically to the assembly line *HD Colorful Upper Contraposition CCD vision system *Imported electrical configuration		

Full Automatic LCD Equipment						
NO.	Category	Picture	Specification		Function	Price
	Automatic COG bonding line		<div>Model: FAC001</div> <div>Product Name: 1-7inch Full Automatic COG bonding line</div> <div>Suitable For: Suitable for IC Bonding to the LCD, ACF attach, IC preload and the pressure completed in one time</div> <div>Size Range: 1-7 inch</div> <div>Bonding precision: ±2.5UM</div> <div>Pressure Precision: ±5UM</div> <div>IC Size: L:2-40mm,W:0.8-3mm</div> <div>Attach Qty: 1PCS</div> <div>Machine Capacity: 1000pcs/H</div> <div>Power Supply: 220V±10%,50HZ,1000W</div> <div>Air Supply: 0.5-0.7MPa,dry air</div> <div>Temp Range: 1-300℃</div> <div>Time Range: 1-99.9sec</div> <div>Product Size: W1500*D2300*H1700MM</div> <div>N.W:</div> <div>Packing Size:</div> <div>G.W:</div>		<div>*Constant temperature heating system</div> <div>*Panasonic PLC Control system</div> <div>*Human - Machine interface</div> <div>*Imported electrical configuration</div> <div>*High Precision contraposition system</div> <div>*Include the glass cleaning,ACF pre-attaching,COG pre-bonding,COG main-bonding processes. COG process all in one machine</div>	
	Automatic FOG bonding line		<div>Model: FAF001</div> <div>Product Name: Automatic FOG bonding line</div> <div>Suitable For: Suitable for FPC Bonding to the LCD, ACF attach, FPC Pre-press and the pressure completed in one time</div> <div>Size Range: 1-7 inch</div> <div>Bonding Precision: ±0.005MM</div> <div>Pressure Precision: ±0.01MM</div> <div>Attach Qty: 1pcs</div> <div>Machine Capacity: 1000pcs/H</div> <div>Power Supply: 220V±10%,50HZ,1000W</div> <div>Air Supply: 0.5-0.7MPa,dry air</div> <div>Temp Range: 1-300℃</div> <div>Time Range: 1-99.9sec</div> <div>Product Size: W1500*D2500*H1700MM</div> <div>N.W:</div> <div>Packing Size:</div> <div>G.W:</div>		<div>*Constant temperature heating system</div> <div>*Panasonic PLC Control system</div> <div>*Human - Machine interface</div> <div>*Imported electrical configuration</div> <div>*High Precision contraposition system</div>	
Auxiliary Equipment&Accessories						
NO.	Category	Picture	Specification		Function	Price
	Manual IC disassembling M/C		<div>Model: ID01A</div> <div>Product Name: Manual IC disassembling M/C</div> <div>Suitable For: Suitable for Disassembling 2-12inch LCD IC</div> <div>Heating Power: 750W</div> <div>Disassembly speed: 4S/pcs</div> <div>Power Supply: 220V±10%,50HZ,200W</div> <div>Platform Size: 300*250MM</div> <div>Product Size: 400*200*500MM</div> <div>N.W:</div> <div>Packing Size:</div> <div>G.W: about 25kg</div>			
	High-precision press head Customized		High Precision indenters, stainless steel indenter, brass indenter, ceramic indenter, tungsten steel indenter, Pulse indenter			